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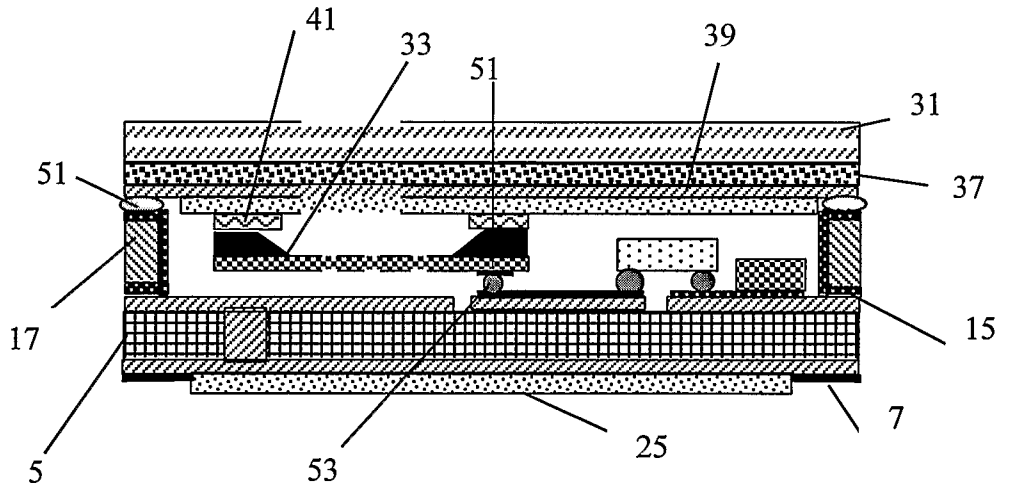
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(54) **Title:** A PACKAGING METHOD FOR MEMS DEVICES, AND MEMS PACKAGES PRODUCED USING THE METHOD



(57) **Abstract:** A MEMS package is proposed in which, a MEMS device (33) is located on a first flex substrate (31), and one of more electronic components (typically, an application specific IC (ASIC) (1) and one or more passive components are located on a second substrate (5). The two substrates (5, 31) are the mutually connected in parallel, sandwiching the MEMS device (33) and the one or more electronic components between then. The substrates (5, 31) are spaced apart by a conductive element (17). The conductive element (17), and conductive layers of the substrates (5, 31), provide a Faraday cage protecting the contents of the package from EMI noise.

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